

Multifunctional Manual Wire Bonder

Model: SA-MMWB-450B

SA-MMWB-450B is a multifunctional manual wire bonder. It delivers stable ultrasonic output with closed-loop force control and electric-driven design requiring no compressed air. It supports tailless bumping and deep-access bonding, and adapts well to soft substrates for microwave components, lasers, optical communications, sensors, MEMS and power devices.



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SA-MMWB-450B

Feature

- Close loop force control
- EFO controlled by CPLD
- DSP phase lock, stable ultrasonic output
- Drive by electricity without compressed air
- Self-study GUI for advanced process
- Unique tailless bumping process and super adaptability for soft substrates
- Bond head designed by parallelogram support large module of deep access

Application

- Microwave components
- Lasers
- Optical communication devices
- Sensors
- MEMS
- RF modules
- SAW devices
- Power devices
- Discrete devices

Specifications:

Parameter	Descriptions
Bonding Wire Type	Au(15~75μm), Pt(18~25μm), Ag(18~50μm)
Cavity Depth	12mm(max.)
Capillary Length	16mm/19mm
Spool Diameter	1/2inch(standard), 2inches(optional)
Bonding Force	1~250g
Bond Power	Numerical control, 1000x subdivision
Clamping Table	Maximum Temperature 200℃
Bond Head Z Range	18mm
Bond Head X-Y Range	X=15mm, Y=15mm
Lifting Table Z Range	0~18mm
Lifting Table X-Y Range	250mm×270mm
Weight	47kg(GW.), 70kg(NW.)
Input Voltage	220V±10% @ 50~60Hz
Power Consumption	≤500W
Size(L×W×H)	640mm×620mm×450mm